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Osaki et al.

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(54) **METHOD FOR MANUFACTURING ORGANIC EL DEVICE AND ORGANIC EL DEVICE**

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257/E51.046; 438/46, 82, 99
See application file for complete search history.

(71) Applicant: **NITTO DENKO CORPORATION**,
Ibaraki-shi, Osaka (JP)

(72) Inventors: **Yoshinori Osaki**, Ibaraki (JP);
Shigenori Morita, Ibaraki (JP)

(73) Assignee: **NITTO DENKO CORPORATION**,
Ibaraki-shi (JP)

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(2013.01); **H01L 51/5012** (2013.01); **H01L**
51/524 (2013.01); **H01L 51/529** (2013.01);
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(2013.01)

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CPC H01L 51/5296; H01L 51/524; H01L
51/5287; H01L 51/5012; H01L 51/5259;
H01L 51/5225

(56) **References Cited**

U.S. PATENT DOCUMENTS

2003/0178937 A1 9/2003 Mishima
2010/0244073 A1* 9/2010 Ito et al. 257/98

(Continued)

FOREIGN PATENT DOCUMENTS

DE 102010003121 A 9/2011
EP 2 744 305 A1 6/2014

(Continued)

OTHER PUBLICATIONS

Notification Concerning Transmittal of International Preliminary
Report on Patentability (Form PCT/IB/326) of International Appli-
cation No. PCT/JP2013/055379 mailed Sep. 12, 2014 with Forms
PCT/IB/373, PCT/IB/338 and PCT/ISA/237.

(Continued)

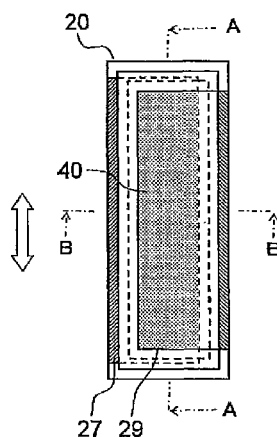
Primary Examiner — Jasmine Clark

(74) *Attorney, Agent, or Firm* — Westerman, Hattori,
Daniels & Adrian, LLP

(57) **ABSTRACT**

Provided is a method for manufacturing an organic EL device
which suppresses a deterioration in the light emission prop-
erties. In this method, while first and second electrode layers
are prevented from being in contact with each other, an
organic layer is allowed to protrude from the first electrode
layer toward at least both outer sides in the longitudinal
direction of a substrate. Further, the second electrode layer is
allowed to protrude from the organic layer toward at least
both outer sides in the longitudinal direction. Thereby, the
first electrode layer, the organic layer, and the second elec-
trode layer are formed so that both end edges of the organic
layer in a longitudinal direction of the substrate are covered
by both end sides of the second electrode layer in the longi-
tudinal direction, on at least both outer sides of the light
emitting part in the longitudinal direction.

4 Claims, 6 Drawing Sheets



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FOREIGN PATENT DOCUMENTS

JP 2002-25763 A 1/2002

JP 3942017 B2 7/2007

JP 2009301965 A 12/2009

WO 2009/025286 A1 2/2009

WO 2011/001567 A1 1/2011

WO 2011/117073 A2 9/2011

WO 2013/024707 A1 2/2013

(56) **References Cited**

U.S. PATENT DOCUMENTS

2010/0258797 A1 * 10/2010 Yamamoto H01L 51/56
257/43

2011/0073848 A1 * 3/2011 Takada et al. 257/40

2011/0101401 A1 5/2011 Aratani et al. 257/40

2011/0186822 A1 * 8/2011 Adachi 257/40

2012/0074398 A1 3/2012 Fujita

2012/0132950 A1 * 5/2012 Yamamuro et al. 257/99

2013/0009199 A1 1/2013 Ingle et al.

2013/0153936 A1 * 6/2013 Nishiyama H01L 51/0018
257/88

2013/0313537 A1 11/2013 Aratani et al.

OTHER PUBLICATIONS

International Search Report dated Jun. 4, 2013 issued in correspond-
ing application No. PCT/JP2013/055379.Chinese Office Action dated Oct. 30, 2015 issued in counterpart
Japanese patent application No. 201380011467.X (6 pages).European Search Report dated Sep. 21, 2015 issued in counterpart EP
patent application No. 13754199.1. (6 pages).

* cited by examiner

Fig. 1 (a)

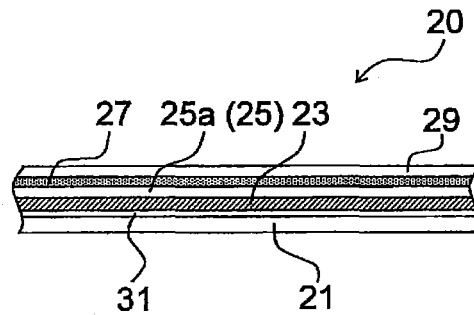


Fig. 1 (b)

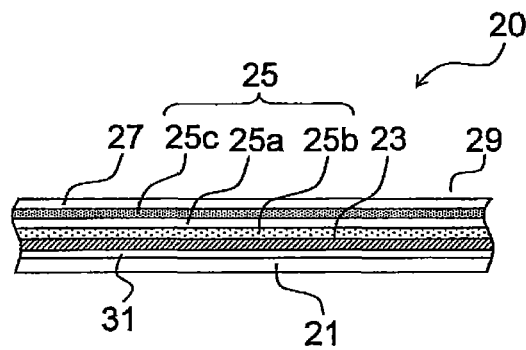
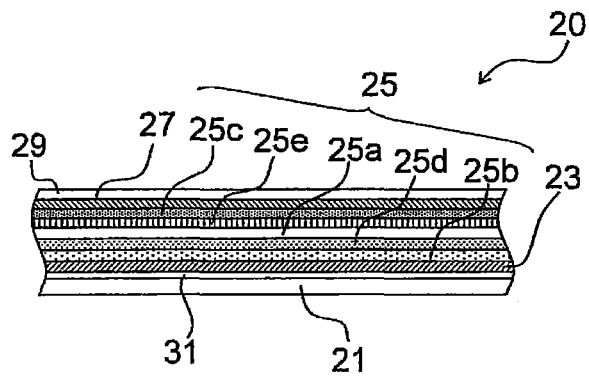
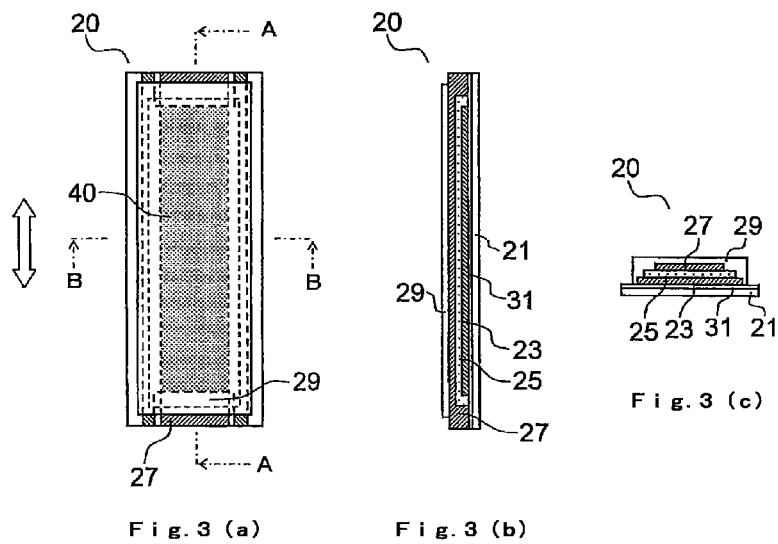
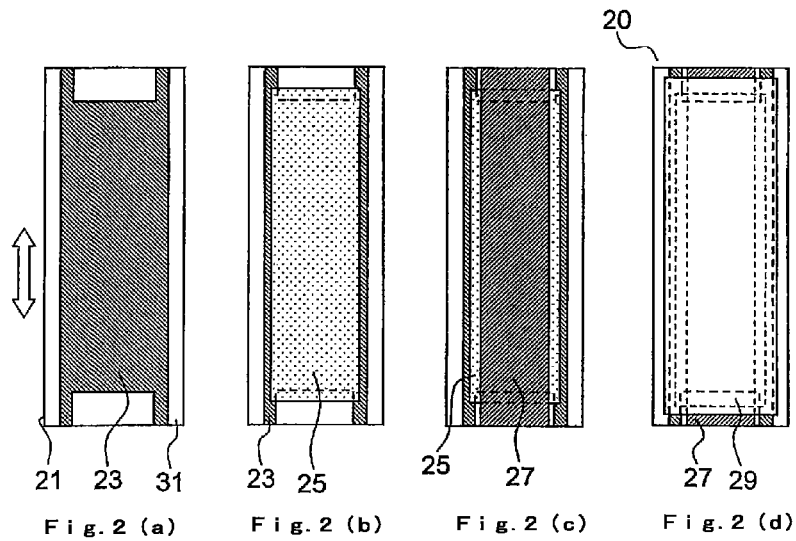
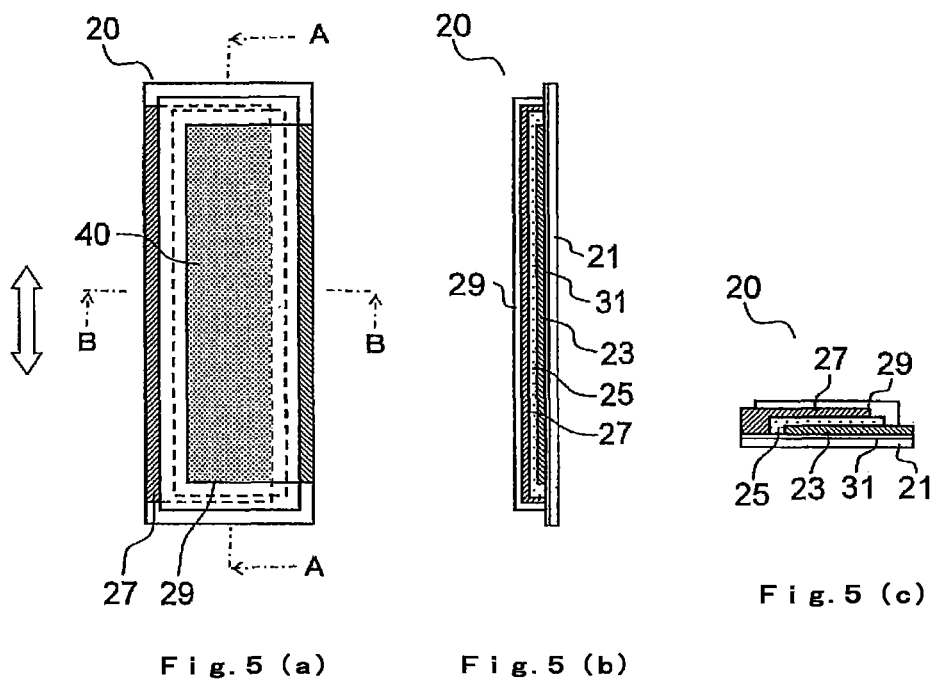
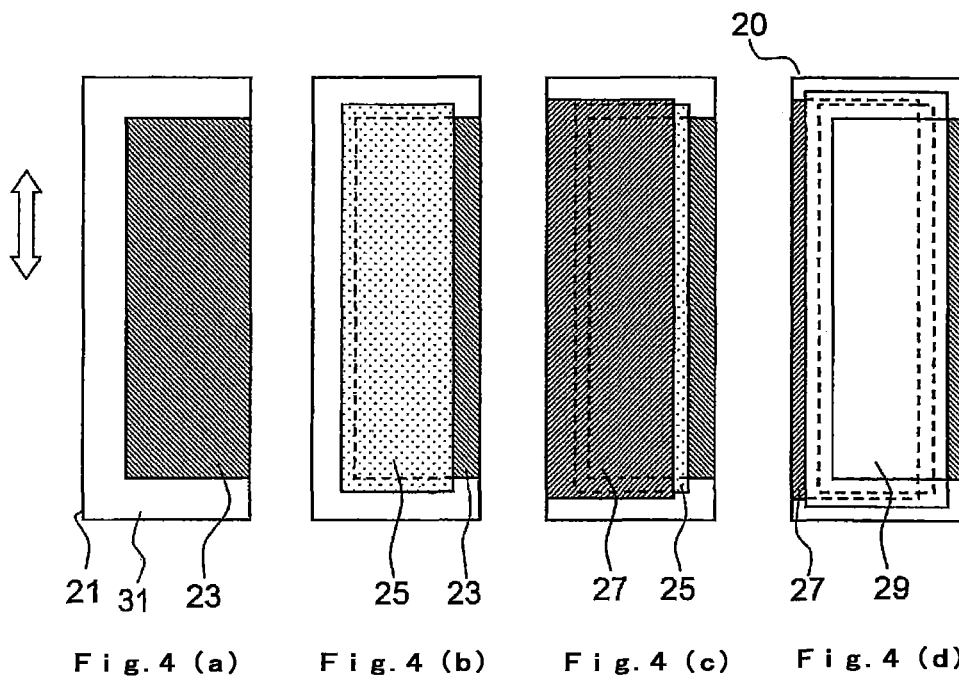


Fig. 1 (c)







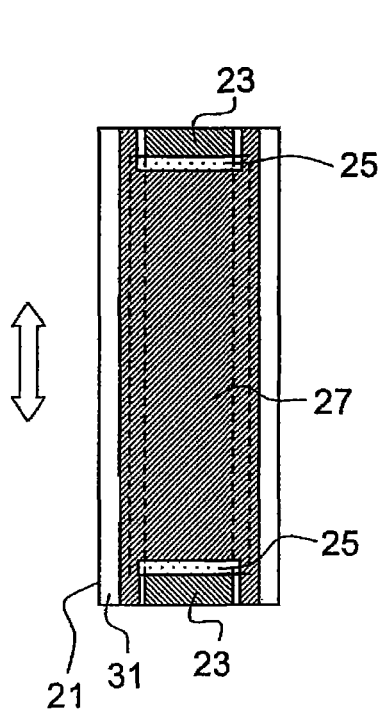


Fig. 6 (a)

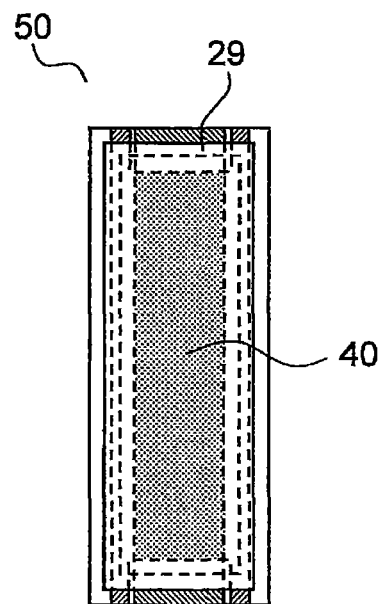


Fig. 6 (b)

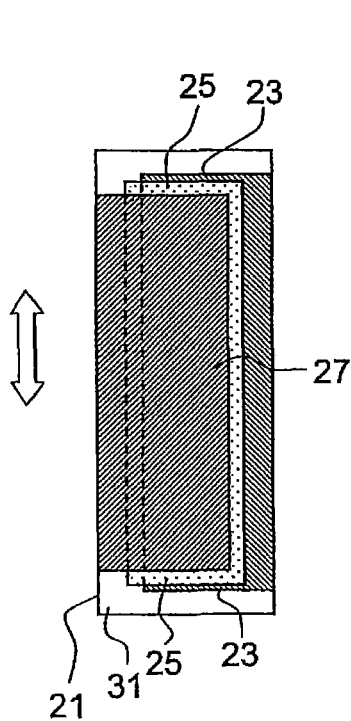


Fig. 7 (a)

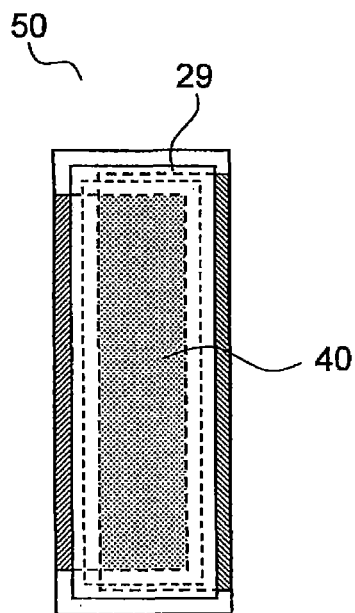


Fig. 7 (b)

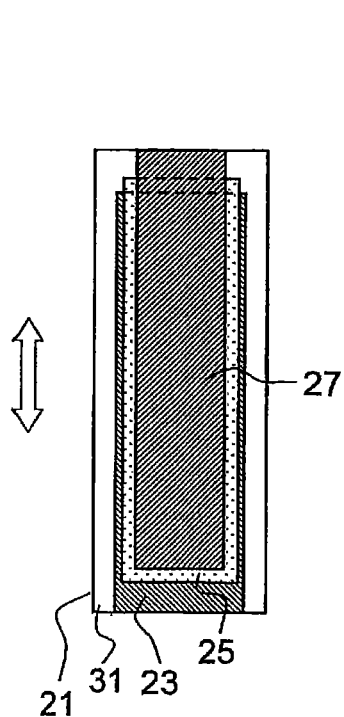


Fig. 8 (a)

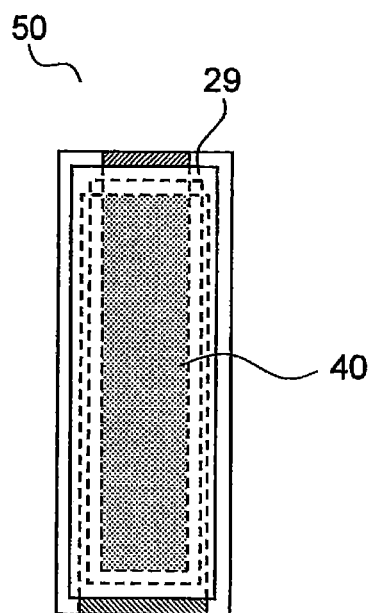


Fig. 8 (b)

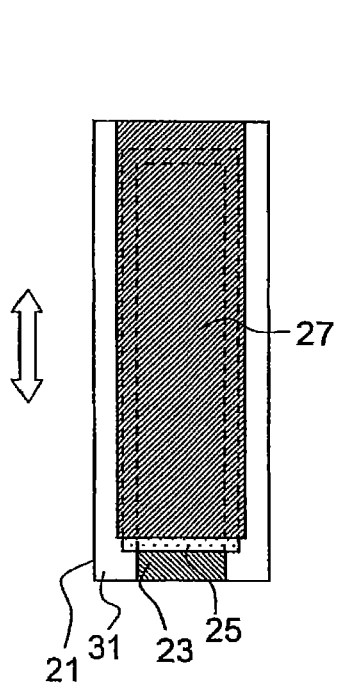


Fig. 9 (a)

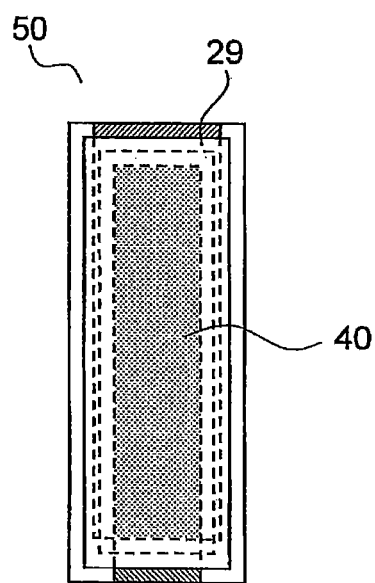


Fig. 9 (b)

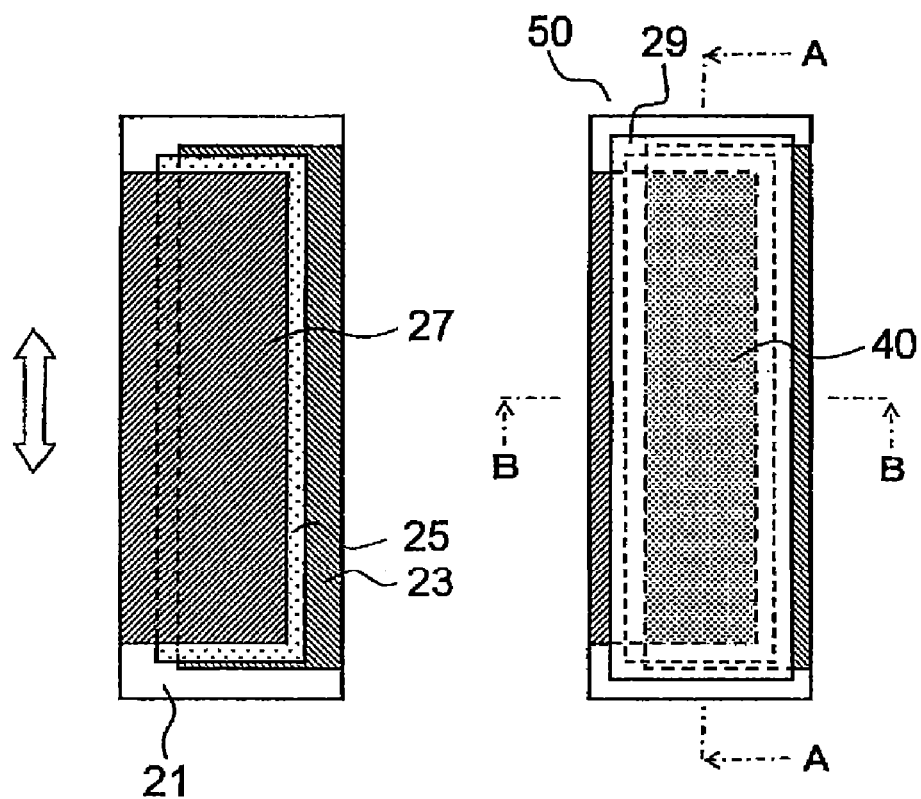


Fig. 10 (a)

Prior Art

Fig. 10 (b)

Prior Art

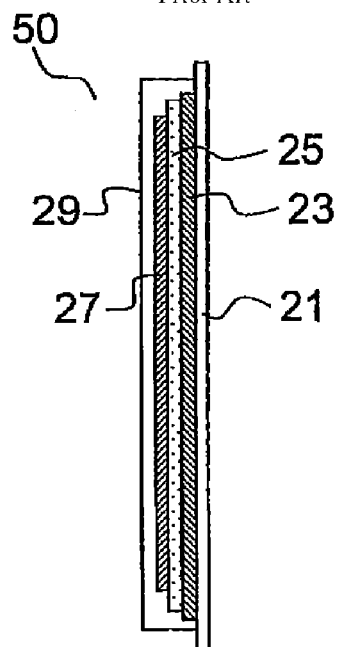


Fig. 10 (c)

Prior Art

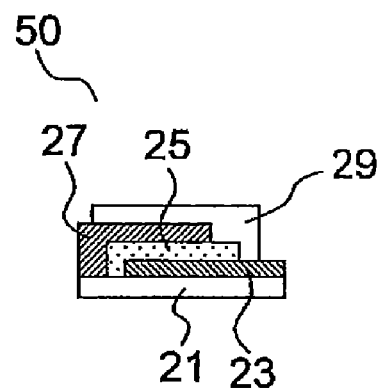


Fig. 10 (d)

Prior Art

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METHOD FOR MANUFACTURING ORGANIC EL DEVICE AND ORGANIC EL DEVICE

CROSS-REFERENCE TO RELATED APPLICATIONS

This application claims priority to Japanese Patent Applications Nos. 2012-041700 and 2013-023502, the disclosures of which are incorporated herein by reference in their entirety.

FIELD

The present invention relates to a method for manufacturing an organic EL device and an organic EL device, in which an electrode layer and an organic layer are formed on a substrate, and the organic layer is configured to emit light.

BACKGROUND

Conventionally, organic EL (electroluminescence) devices are known as devices to be used for light emitting displays, etc. Such an organic EL device basically has an organic layer having at least a light emitting layer as an organic constituent layer and a pair of electrode layers.

An example of the organic EL device is shown in FIG. 10. As shown in FIG. 10, a conventional organic EL device 50 is formed by sequentially stacking a first electrode layer 23 (for example, an anode layer), an organic layer 25 having at least a light emitting layer as an organic constituent layer, and a second electrode layer 27 (for example, a cathode layer) on one surface of a substrate 21 as constituent layers of the device (see FIG. 10(a)), and subsequently stacking a sealing layer 29 (see FIGS. 10(b) to (d)). Further, the organic EL device 50 has a portion in which the first electrode layer 23, the organic layer 25, and the second electrode layer 27 overlap and which serves as a light emitting part 40.

Furthermore, the first electrode layer 23 and the second electrode layer 27 are formed to protrude outwardly from the sealing layer 29 so as not to overlap each other, so that they can be energized from the outside with no short circuit therebetween.

For example, on the right side of FIG. 10(b), the right end side of the organic layer 25 protrudes from the right end edge of the second electrode layer 27 toward the right side so that the first electrode layer 23 can be energized with no short circuit, as described above. Further, the right end side of the first electrode layer 23 protrudes from the right end edge of the organic layer 25 toward the right side (see the right side of FIG. 10(a)). Furthermore, the right end side of the first electrode layer is formed to protrude from the right end edge of the sealing layer 29 toward the right side (see the right side of FIG. 10(d)).

Further, on the left side of FIG. 10(b), the left end side of the organic layer 25 protrudes from the left end edge of the first electrode layer 23 toward the left side so that the second electrode layer 27 can be energized with no short circuit, as described above. Further, the left end side of the second electrode layer 27 protrudes from the left end edge of the organic layer 25 toward the left side (see the left side of FIG. 10(a)). Furthermore, the second electrode layer 27 is formed to protrude from the left end edge of the sealing layer 29 toward the left side (see the left side of FIG. 10(d)).

In such an organic EL device of this type, a substrate made of an organic resin is used as a substrate for flexibility. In this case, there are cases where oxygen or moisture permeates through the substrate so as to penetrate into the above

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described constituent layer side, thereby causing a deterioration in light emission properties of the organic EL device over time.

Therefore, it has been proposed that oxygen or moisture is prevented from permeating through the substrate by using a substrate made of metal (see Patent Literatures 1 and 2). Further, in the case of using such a substrate made of metal, an insulating layer is formed on the substrate in order to prevent a short circuit due to contact between the substrate made of metal and the aforementioned first electrode layer.

CITATION LIST

Patent Literature

Patent Literature 1: JP 2002-025763 A
Patent Literature 2: JP 3942017 B2

SUMMARY

Technical Problem

However, even in the case of forming such an insulating layer as above on the substrate made of metal, there are cases where oxygen or moisture penetrates at the boundary between the organic layer and the electrode layer from the end edge sides, thereby generating a region that does not emit light (dark frame) in the light emitting part over time, resulting in a deterioration in the light emission properties.

In view of such problems, it is an object of the present invention to provide a method for manufacturing an organic EL device and an organic EL device, in which the deterioration in the light emission properties is suppressed.

Solution to Problem

Diligent studies by the inventors to solve the aforementioned problems have revealed the following findings.

That is, a strip-shaped metal substrate is generally formed by rolling the substrate in the longitudinal direction. It has been found that a plurality of fine grooves extending in the longitudinal direction are formed on a surface of the substrate across the width direction by the rolling.

Further, also after the insulating layer is stacked on the substrate, grooves formed due to the grooves of the substrate are found to extend in the longitudinal direction on a surface of the insulating layer stacked on the substrate.

Therefore, when an organic EL device is formed using such a substrate, lands formed between the plurality of grooves on the surface of the insulating layer are in contact mainly with the sealing layer, on both outer sides of the light emitting part in the width direction of the substrate. It has been found that such contact makes it difficult for oxygen or moisture to penetrate into the inside of the sealing layer from the outside in the width direction, thereby making their influence on the deterioration in the light emission properties comparatively less.

In contrast, it has been revealed that, on both outer sides of the light emitting part in the longitudinal direction of the substrate, the influence on the deterioration in the light emission properties significantly differs depending on the formed pattern of the organic layer and the second electrode layer.

Specifically, on at least one of both outer sides of the light emitting part in the longitudinal direction, the second electrode layer does not protrude outwardly from the organic layer. In the case where both end edges of the organic layer are not covered by the second electrode layer (see FIG. 6 to FIG.

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10), oxygen or moisture passes through the aforementioned grooves on the surface of the insulating layer so as to penetrate into the inside of the sealing layer. Furthermore, oxygen or moisture penetrates from the end edge sides into a region corresponding to the light emitting part, at the boundary between the organic layer and the first electrode layer, or the boundary between the organic layer and the second electrode layer. It has been found that this causes the deterioration in the light emission properties.

On the other hand, in the case where the second electrode layer protrudes from the organic layer, and both end edges of the organic layer are covered by both end sides of the second electrode layer, on both outer sides of the light emitting part in the longitudinal direction (see FIG. 2 to FIG. 5), even if oxygen or moisture passes through the grooves on the surface of the insulating layer so as to penetrate into the inside of the sealing layer, they can be suppressed from penetrating further inward by the second electrode layer. Therefore, it has been found that the reaching of oxygen or moisture to the boundary between the organic layer and the second electrode layer is made difficult, and the reaching of oxygen or moisture to the light emitting part is made difficult.

On the basis of such findings, the inventors have accomplished the present invention.

That is, a method for manufacturing an organic EL device according to the present invention includes: sequentially forming an insulating layer, a first electrode layer, an organic layer having at least a light emitting layer as an organic constituent layer, a second electrode layer, and a sealing layer, on one surface of a strip-shaped metal substrate; and thereby manufacturing the organic EL device having a portion in which the first electrode layer, the organic layer, and the second electrode layer overlap and which serves as a light emitting part. In this method, while the first electrode layer and the second electrode layer are prevented from being in contact with each other, the first electrode layer, the organic layer, and the second electrode layer are formed so that both end edges of the organic layer in a longitudinal direction of the substrate are covered by both end sides of the second electrode layer in the longitudinal direction, on at least both outer sides of the light emitting part in the longitudinal direction, by allowing the organic layer to protrude from the first electrode layer toward at least both outer sides of the substrate in the longitudinal direction of the substrate and further allowing the second electrode layer to protrude from the organic layer toward at least both outer sides of the substrate in the longitudinal direction.

Further, an organic EL device according to the present invention includes: an insulating layer; a first electrode layer; an organic layer having at least a light emitting layer as an organic constituent layer; a second electrode layer; and a sealing layer, which are sequentially formed on one surface of a strip-shaped metal substrate, the organic EL device having a portion in which the first electrode layer, the organic layer, and the second electrode layer overlap and which serves as a light emitting part. In the organic EL device, the first electrode layer and the second electrode layer are not in contact with each other, and both end edges of the organic layer in the longitudinal direction of the substrate are covered by both end sides of the second electrode layer in the longitudinal direction, on at least both outer sides of the light emitting part in the longitudinal direction of the substrate, with a configuration where the organic layer protrudes from the first electrode layer toward at least both outer sides in a longitudinal direction of the substrate, and the second electrode layer also protrudes from the organic layer toward at least both outer sides in the longitudinal direction.

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Further, in the organic EL device and its manufacturing method according to the present invention, it is desirable that the substrate have a surface roughness in the longitudinal direction that is smaller than a surface roughness in the lateral direction.

BRIEF DESCRIPTION OF DRAWINGS

FIG. 1 depicts schematic partial side sectional views schematically showing examples of a layer configuration of an organic EL device.

FIG. 1(a) is a view in the case of an organic layer having a single layer.

FIG. 1(b) is a view in the case of an organic layer having three layers.

FIG. 1(c) is a view in the case of an organic layer having five layers.

FIG. 2(a) is a schematic plan view schematically showing the state where an anode layer is formed when manufacturing an organic EL device of Example 1 and Example 3.

FIG. 2(b) is a schematic plan view schematically showing the state where an organic layer is formed.

FIG. 2(c) is a schematic plan view schematically showing the state where a cathode layer is formed.

FIG. 2(d) is a schematic plan view schematically showing the state where a sealing layer is formed.

FIG. 3(a) is a schematic plan view schematically showing the organic EL device of Example 1 and Example 3.

FIG. 3(b) is a cross sectional view taken along the line A-A in FIG. 3(a), as seen in the direction of the arrows.

FIG. 3(c) is a cross sectional view taken along the line B-B in FIG. 3(a), as seen in the direction of the arrows.

FIG. 4(a) is a schematic plan view schematically showing the state where an anode layer is formed when manufacturing an organic EL device of Example 2.

FIG. 4(b) is a schematic plan view schematically showing the state where an organic layer is formed.

FIG. 4(c) is a schematic plan view schematically showing the state where a cathode layer is formed.

FIG. 4(d) is a schematic plan view schematically showing the state where a sealing layer is formed.

FIG. 5(a) is a schematic plan view schematically showing the organic EL device of Example 2.

FIG. 5(b) is a cross sectional view taken along the line A-A in FIG. 5(a), as seen in the direction of the arrows.

FIG. 5(c) is a cross sectional view taken along the line B-B in FIG. 5(a), as seen in the direction of the arrows.

FIG. 6(a) is a schematic plan view schematically showing the state before a sealing layer is formed when manufacturing an organic EL device of Comparative Example 1 and Comparative Example 5.

FIG. 6(b) is a schematic plan view schematically showing the state where a sealing layer is formed.

FIG. 7(a) is a schematic plan view schematically showing the state before a sealing layer is formed when manufacturing an organic EL device of Comparative Example 2.

FIG. 7(b) is a schematic plan view schematically showing the state where a sealing layer is formed.

FIG. 8(a) is a schematic plan view schematically showing the state before a sealing layer is formed when manufacturing an organic EL device of Comparative Example 3.

FIG. 8(b) is a schematic plan view schematically showing the state where a sealing layer is formed.

FIG. 9(a) is a schematic plan view schematically showing the state before a sealing layer is formed when manufacturing an organic EL device of Comparative Example 4.

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FIG. 9(b) is a schematic plan view schematically showing the state where a sealing layer is formed.

FIG. 10(a) is a schematic plan view schematically showing the state before a sealing layer is formed when manufacturing a conventional organic EL device.

FIG. 10(b) is a schematic plan view schematically showing the state where a sealing layer is formed.

FIG. 10(c) is a cross sectional view taken along the line A-A in FIG. 10(b), as seen in the direction of the arrows.

FIG. 10(d) is a cross sectional view taken along the line B-B in FIG. 10(b), as seen in the direction of the arrows.

DESCRIPTION OF EMBODIMENTS

Hereinafter, a method for manufacturing an organic EL device and an organic EL device according to the present invention are described with reference to the drawings.

As shown in FIG. 1(a) the method for manufacturing an organic EL device according to this embodiment, an insulating layer 31, a first electrode layer (which herein is an anode layer) 23, an organic layer 25 having at least a light emitting layer 25a as an organic constituent layer, a second electrode layer 27 (which herein is a cathode layer), and a sealing layer 29 are sequentially formed on one surface of a strip-shaped metal substrate 21. Thus, an organic EL device 20 having a portion in which the anode layer 23, the organic layer 25, and the cathode layer 27 overlap and which serves as a light emitting part 40 is manufactured. Further, in the method for manufacturing an organic EL device, while the anode layer 23 and the cathode layer 27 are prevented from being in contact with each other, the organic layer 25 is allowed to protrude from the anode layer 23 toward at least both outer sides in the longitudinal direction of the substrate 21. Further, in the method for manufacturing an organic EL device, the cathode layer 27 is allowed to protrude from the organic layer 25 toward at least both outer sides thereof in the longitudinal direction. Thereby, the anode layer 23, the organic layer 25, and the cathode layer 27 are formed so that both end edges of the organic layer 25 in the longitudinal direction are covered by both end sides of the cathode layer 27 in the longitudinal direction, on at least both outer sides of the light emitting part 40 in the longitudinal direction of the substrate 21.

As a metal material for the substrate 21, any metal can be used as long as it is formable into a strip-shaped sheet by rolling at room temperature and normal pressure, such as stainless steel, Fe, Al, Ni, Co, and Cu, and alloys thereof.

As the insulating layer 31, an organic insulating layer or an inorganic insulating layer can be used, for example.

As a material for forming the organic insulating layer, an insulating resin can be used. Since the substrate 21 may be heated to 150 to 300° C. in the manufacturing process of the organic EL device in some cases, it is preferable to use a heat resistant resin having a glass transition temperature of 150° C. or more as a material for the organic insulating layer. Specific examples of the heat resistant resin include acrylic resin, norbornene resin, epoxy resin, polyimide resin, polyamide-imide resin, polyamide resin, polyester resin, polyarylate resin, polyurethane resin, polycarbonate resin, polyether ketone resin, and polyphenylsulfone resin, and resin composites thereof. Among these, it is preferable that the heat resistant resin be at least one selected from the group consisting of acrylic resin, norbornene resin, epoxy resin, and polyimide resin.

When the organic insulating layer has an excessively small thickness, the surface roughness of the metal substrate 21 cannot be sufficiently flattened in some cases. When it has an excessively large thickness, the adhesion to the metal sub-

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strate 21 may be reduced in some cases. From such viewpoints, the thickness of the organic insulating layer is preferably in the range of 1 to 40 μm. When the thickness is within this range, it is possible to ensure not only sufficient electrical insulating properties but also sufficient adhesion to the substrate 21. The thickness of the organic insulating layer is more preferably 0.5 to 10 μm, further preferably 1 to 5 μm. The method for forming the organic insulating layer on the substrate 21 is not specifically limited, and the organic insulating layer can be formed, for example, by coating such as roller coating, spraying coating, spin coating, and dipping, or by transferring resin in the form of a film.

As a material for forming the inorganic insulating layer, an inorganic material having insulating properties can be used. Further, it is preferable that the inorganic material have gas barrier properties. It is preferable that the inorganic material contain at least one of metal and semimetal, for example. Further, it is preferable that the at least one of metal and semimetal be at least one selected from the group consisting of oxide, nitride, carbide, oxynitride, oxycarbide, nitride carbide, and oxynitride carbide. Examples of the metal include zinc, aluminum, titanium, copper, and magnesium. Examples of the semimetal include silicon, bismuth, and germanium.

When the inorganic insulating layer has an excessively small thickness, the insulating properties decrease. Meanwhile, when the inorganic insulating layer has an excessively large thickness, cracks tend to occur, and gas barrier properties and insulating properties decrease. The thickness of the inorganic insulating layer is preferably in the range of 10 nm to 5 μm, more preferably in the range of 50 nm to 2 μm, further preferably in the range of 0.1 to 1 μm. The method for forming the inorganic insulating layer is not specifically limited, and dry methods, such as vapor deposition using an evaporation source capable of discharging an inorganic insulating layer-forming material, sputtering, and CVD, and wet methods such as a sol-gel method can be used.

As a material for forming the anode layer 23 (anode layer-forming material), indium-tin oxide (ITO) and zinc oxide materials such as indium-zinc oxide (IZO), zinc oxide (ZnO), gallium doping zinc oxide (GZO), and antimony doping zinc oxide (AZO) can be used.

The method for forming the anode layer 23 on the insulating layer 31 is not specifically limited, and common vapor deposition using an evaporation source capable of discharging an anode layer-forming material can be used, for example. In such vapor deposition, it is preferable to use thermal deposition.

The organic layer 25 has at least the light emitting layer 25a as an organic constituent layer. The organic layer 25 is composed of a single organic constituent layer, or a stack of a plurality of organic constituent layers. In the case where the organic layer 25 is composed of a single organic constituent layer, the organic constituent layer is the above described light emitting layer 25a. In the case where the organic layer is composed of a plurality of organic constituent layers, the plurality of organic constituent layers are composed of the light emitting layer 25a and organic constituent layers other than the light emitting layer 25a. Further, examples of the organic constituent layers other than the light emitting layer 25a include a hole injection layer 25b, a hole transporting layer 25d, an electron injection layer 25c, and an electron transporting layer 25e.

In this way, the organic layer 25 is not specifically limited as long as it has at least the light emitting layer 25a as its organic constituent layer. The organic layer 25 can be formed by stacking a plurality of organic constituent layers, as needed. For example, as shown in FIG. 1(b), the organic layer

may be formed as a three-layered stack by stacking the hole injection layer **25b**, the light emitting layer **25a**, and the electron injection layer **25c** in this order. Other than that, the organic layer may be formed as a four-layered stack by interposing the hole transporting layer **25d** between the light emitting layer **25a** and the hole injection layer **25b** shown above in FIG. **1(b)** (see FIG. **1(c)**), or by interposing the electron transporting layer **25e** between the light emitting layer **25a** and the electron injection layer **25c** (see FIG. **1(c)**), as needed.

Furthermore, as shown in FIG. **1(c)**, the organic layer may be formed as a five-layered stack by interposing the hole transporting layer **25d** between the hole injection layer **25b** and the light emitting layer **25a**, and interposing the electron transporting layer **25e** between the light emitting layer **25a** and the electron injection layer **25c**. Further, the film thickness of each layer is generally designed to be about several nm to several tens of nm. However, such film thickness is appropriately designed corresponding to an organic layer-forming material, the light emission properties, or the like, and thus is not specifically limited.

Examples of a material for forming the light emitting layer **25a** include tris-(8-quinolinol) aluminum (Alq3), and [2-tert-butyl-6-[2-(2,3,6,7-tetrahydro-1,1,7,7-tetramethyl-1H,5H-benzo[*ij*]quinolizin-9-yl)vinyl]-4H-pyran-4-ylidene]malononitrile (DCJTb).

The hole injection layer **25b** is a layer that facilitates the injection of holes from the anode layer **23** into the light emitting layer **25a** or the hole transporting layer **25d**. Examples of a material for forming the hole injection layer **2b** include HAT-CN (1,4,5,8,9,12-hexaazatriphenylene hexacarbonitrile), copper phthalocyanine (CuPc), and N,N'-di(1-naphthyl)-N,N'-diphenyl-1,1'-biphenyl-4,4'-diamine (α -NPD).

The hole transporting layer **25d** is a layer that has at least one of a function to transport holes and a function to suppress the migration of electrons injected from the cathode layer **27** to the anode layer **23**. Examples of a material for forming the hole transporting layer **25d** include N,N'-bis(naphthalene-1-yl)-N,N'-bis(phenyl)-benzidine (NPB), N,N'-di(1-naphthyl)-N,N'-diphenyl-1,1'-biphenyl-4,4'-diamine (α -NPD), N,N,N',N'-tetraphenyl-4,4'-diaminophenyl, and N,N'-diphenyl-N,N'-bis(3-methylphenyl)-[1,1'-biphenyl]-4,4'-diamine (TPD).

The electron injection layer **25c** is a layer that facilitates the injection of electrons from the cathode layer **27** into the light emitting layer **25a** or the electron transporting layer **25e**. Examples of a material for forming the electron injection layer **25c** include lithium fluoride (LiF) and cesium fluoride (CsF).

The electron transporting layer **25e** is a layer that has at least one of a function to transport electrons and a function to suppress the migration of holes injected from the anode layer **23** to the cathode layer **27**. Examples of a material for forming the electron transporting layer **25e** include tris-(8-quinolinol) aluminum (Alq3).

The method for forming the organic layer **25** on the anode layer **23** is not specifically limited, and common vapor deposition using an evaporation source capable of discharging an organic layer-forming material can be used, for example. In such vapor deposition, it is preferable to use thermal deposition.

Examples of a material for forming the cathode layer **27** (cathode layer-forming material) include aluminum (Al), magnesium silver (Mg/Ag), ITO, and IZO.

The method for forming the cathode layer **27** on the organic layer **25** is not specifically limited, and vapor deposition using an evaporation source capable of discharging a cathode layer-

forming material can be used, for example. In addition, a film forming method by sputtering also can be used, for example.

Examples of a material for forming the sealing layer **29** (sealing layer-forming material) include SiOCN, SiN, and SiON.

The method for forming the sealing layer **29** on the cathode layer **27** is also not specifically limited, and vapor deposition using an evaporation source capable of discharging a sealing layer-forming material can be used, for example. In such vapor deposition, it is preferable to use plasma assisted deposition, for example.

In the method for manufacturing an organic EL device of this embodiment, a stack of the substrate **21** and the insulating layer **31** formed on one surface of the substrate **21** is formed in advance, and the anode layer **23**, the light emitting layer **25a**, the cathode layer **27**, and the sealing layer **29** are sequentially deposited on the insulating layer **31** of the stack. Other than that, the insulating layer **31** may be formed, using an evaporation source for forming the insulating layer **31**, on the substrate **21** on which the insulating layer **31** is not stacked in advance, and the anode layer **23**, the light emitting layer **25a**, the cathode layer **27**, and the sealing layer **29** may be sequentially formed on the thus formed insulating layer **31**, as described above.

Specifically, in the method for manufacturing an organic EL device of this embodiment, the insulating layer **31** is first applied onto one surface of the substrate **21** in advance, for example, using a coating apparatus.

Next, the anode layer **23** is formed on the insulating layer **31** of the stack of the substrate **21** and the insulating layer **31** using vapor deposition described above. Subsequently, the light emitting layer **25a** that is an organic layer is formed on the anode layer **23** using vapor deposition described above. Further, the cathode layer **27** is formed on the light emitting layer **25a** using vapor deposition described above. Then, the sealing layer **29** is formed from above the cathode layer **27** so as to cover the thus formed layers using vapor deposition described above. Thus, the organic EL device **20** is formed.

Subsequently, the formation of each layer is described.

The anode layer **23**, the organic layer **25**, the cathode layer **27**, and the sealing layer **29** can be appropriately patterned, for example, by using a conventionally known method, such as a method of allowing each of the constituent layer-forming materials to pass through a shadow mask provided with an opening of a desired shape and interposed between the substrate **21** and each of the evaporation sources described above. Further, examples of the pattern of the constituent layers include the patterns shown in FIG. **2** and FIG. **4**. However, there is no specific limitation to these patterns shown in FIG. **2** and FIG. **4**.

For example, as shown in FIG. **1**, while the anode layer **23** and the cathode layer **27** are prevented from being in contact with each other, the anode layer **23** is first formed on the insulating layer **31** of the aforementioned stack (see FIG. **2(a)**). Next, the organic layer **25** is formed so as to cover the anode layer **23** on at least both outer sides of the light emitting part **40** in the longitudinal direction (direction of the white arrow) of the substrate **21** (see FIG. **2(b)**). Subsequently, the cathode layer **27** is formed so as to protrude from the organic layer **25** toward at least both outer sides and to cover both end edges of the organic layer **25** in the longitudinal direction, on both outer sides thereof (see FIG. **2(c)**). Then, the sealing layer **29** is formed so that parts of the anode layer **23** and the cathode layer **27** protrude therefrom (FIG. **2(d)**). Thus, the organic EL device **20** is formed, and the portion in which the anode layer **23**, the organic layer **25**, and the cathode layer **27** overlap serves as the light emitting part **40** (see FIG. **3**).

Further, as shown in FIG. 2 and FIG. 3, both end edges of the organic layer 25 in the longitudinal direction are covered by both end sides of the cathode layer 27, on both outer sides of the light emitting part 40 in the longitudinal direction.

In FIG. 2 and FIG. 3 as described above, the organic layer 25 protrudes outwardly relative to the cathode layer 27, on both outer sides of the light emitting part 40 in the width direction of the substrate 21 (the left and right directions in FIG. 2 and FIG. 3). Further, the anode layer 23 protrudes outwardly relative to the organic layer 25. Furthermore, the anode layer 23 and the cathode layer 27 thus formed are not in contact with each other.

Alternatively, for example, as shown in FIG. 4, while the anode layer 23 and the cathode layer 27 are prevented from being in contact with each other, the anode layer 23 is first formed on the insulating layer 31 of the aforementioned stack (see FIG. 4(a)). Next, the organic layer 25 is formed so as to cover the anode layer 23 on at least both outer sides of the light emitting part 40 in the longitudinal direction (direction of the white arrow) of the substrate 21 (see FIG. 4(b)). Subsequently, the cathode layer 27 is formed so as to protrude from the organic layer 25 toward at least both outer sides described above and to cover both end edges of the organic layer 25 in the longitudinal direction, on both outer sides described above (see FIG. 4(c)). Then, the sealing layer 29 is formed so that parts of the anode layer 23 and the cathode layer 27 protrude therefrom (see FIG. 4(d)). Thus, the organic EL device 20 is formed, and the portion in which the anode layer 23, the organic layer 25 and the cathode layer 27 overlap serves as the light emitting part 40 (see FIG. 5). Further, as shown in FIG. 4 and FIG. 5, both end edges of the organic layer 25 in the longitudinal direction are covered by both end sides of the cathode layer 27, on both outer sides of the light emitting part 40 in the longitudinal direction.

In FIG. 4 and FIG. 5 as described above, the organic layer 25 protrudes outwardly from the cathode layer 27 on one outer side (the right side in FIG. 4 and FIG. 5) of both outer sides of the light emitting part 40 in the width direction of the substrate 21 (the left and right directions in FIG. 4 and FIG. 5). Further, the anode layer 23 protrudes outwardly from the organic layer 25. In contrast, on the other outer side (the left side in FIG. 4 and FIG. 5), the organic layer 25 protrudes outwardly from the anode layer 23. Further, the cathode layer 27 protrudes outwardly from the organic layer 25. Furthermore, the anode layer 23 and the cathode layer 27 thus formed are not in contact with each other.

In the organic EL device 20 exemplified in FIG. 3 and FIG. 5 above, the portions of the anode layer 23 and the cathode layer 27 protruding from the sealing layer 29 are not in contact with each other. By supplying electricity to such protruding portions, the light emitting part 40 is caused to emit light.

This embodiment employs a configuration in which the light emitting part 40 has a rectangular shape. However, the shape of the light emitting part 40 is not specifically limited.

According to the manufacturing method, the anode layer 23, the organic layer 25, and the cathode layer 27 can be formed, while the anode layer 23 and the cathode layer 27 are prevented from being in contact with each other. Therefore, light emission of the light emitting part 40 is enabled while the short circuit between the anode layer 23 and the cathode layer 27 is avoided. Further, both end edges of the organic layer 25 in the longitudinal direction of the strip-shaped metal substrate 21 are covered by both end sides of the cathode layer 27 in the longitudinal direction, on both outer sides of the light emitting part 40 in the longitudinal direction, thereby making it difficult for oxygen or moisture to reach the boundary between the organic layer 25 and the cathode layer 27,

even if oxygen or moisture passes through the grooves on the surface of the insulating layer 31 that are formed due to the fine grooves extending along the longitudinal direction on the surface of the substrate 21 and thus penetrates into the inside of the sealing layer 29. Therefore, it is possible to suppress the penetration of oxygen or moisture into the inside of the light emitting part 40.

Accordingly, the organic EL device 20 in which the deterioration in the light emission properties is suppressed can be manufactured.

It should be noted that, in the organic EL device 20 exemplified in FIG. 2 to FIG. 5, both end edges of the organic layer 25 are not covered by both end sides of the cathode layer 27 on at least one of the outer sides of the light emitting part 40 in the width direction of the substrate 21. However, since the lands between the grooves formed on the surface of the insulating layer 31 are in contact with the aforementioned constituent layers in the width direction, as described above, the penetration of oxygen or moisture into the inside of the sealing layer 29 can be suppressed.

Further, the above described manufacturing method may be implemented, for example, as follows. A stack of the substrate 21 and the insulating layer 31 wound into a roll is unwound from a feed roller that is a feeding unit. While the substrate 21 of the thus unwound stack is abutted against a surface of a can roll (not shown) and is being conveyed, the anode layer 23, the organic layer 25, the cathode layer 27, and the sealing layer 29 are sequentially formed, as described above, on the insulating layer 31 of the stack supported by the can roll. The thus obtained organic EL device 20 is sequentially wound up on a take-up roller (not shown) that is a collecting unit.

In addition, the above described manufacturing method may be implemented, for example, as follows. The substrate 21 wound into a roll is unwound from the aforementioned feed roller. The insulating layer 31, the anode layer 23, the organic layer 25, the cathode layer 27, and the sealing layer 29 are sequentially formed, as described above, on the thus unwound substrate 21. The thus obtained organic EL device 20 is sequentially wound up on the aforementioned take-up roller.

Further, it is also possible to form the organic EL device 20 in the form of a sheet, for example, by unwinding the organic EL device 20 that is wound up on the take-up roller, as described above, and cutting it.

The organic EL device 20 of this embodiment obtained by the above described manufacturing method is formed by sequentially forming the insulating layer 31, the first electrode layer (which herein is the anode layer 23), the organic layer 25 having at least the light emitting layer 25a as an organic constituent layer, the second electrode layer (which herein is the cathode layer 27), and the sealing layer 29, on one surface of the strip-shaped metal substrate 21. Furthermore, the organic EL device 20 has a portion in which the anode layer 23, the organic layer 25, and the cathode layer 27 overlap and which serves as the light emitting part 40. The anode layer 23 and the cathode layer 27 are not in contact with each other. The organic layer 25 protrudes from the anode layer 23 toward at least both outer sides in the longitudinal direction of the substrate 21. Further, the cathode layer 27 protrudes from the organic layer 25 toward at least both outer sides in the longitudinal direction. Thereby, both end edges of the organic layer 25 in the longitudinal direction of the substrate 21 are covered by both end sides of the cathode layer 27 in the longitudinal direction, on at least both outer sides of the light emitting part 40 in the longitudinal direction.

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The organic EL device **20** is configured to suppress the deterioration, as described above.

The method for manufacturing an organic EL device and the organic EL device of the present invention are as described above. However, the present invention is not limited to the aforementioned embodiments, and the design can be appropriately modified within the scope intended by the present invention.

Further, in the aforementioned embodiments, the first electrode layer is the anode layer **23**, and the second electrode layer is the cathode layer **27**. Other than that, it is also possible to form a cathode layer that serves as the first electrode layer, an organic layer, and an anode layer that serves as the second electrode layer, sequentially on the insulating layer **31** of the aforementioned stack.

EXAMPLES

Next, the present invention is described further in detail by way of examples. However, the present invention is not limited to these examples.

Measurement of Substrate Surface Roughness Ra

Substrate surface roughness (Ra) was measured using a stylus profilometer (product name: Dektak 150). The surface roughness of the substrate was measured at ten points each in the longitudinal direction and in the lateral direction of the substrate, and the average of values measured at the ten points was taken as the substrate surface roughness in the longitudinal direction and in the lateral direction.

Example 1

As a strip-shaped metal substrate, a rolled flexible SUS substrate having a width of 30 mm, a length of 140 m, a thickness of 50 μm , a substrate surface roughness (Ra) in the longitudinal direction of 40 nm, and a substrate surface roughness (Ra) in the lateral direction of 55 nm was used. That is, in Example 1, the substrate surface roughness in the longitudinal direction was smaller than the surface roughness in the lateral direction. An insulating layer having a thickness of 3 μm was formed on one surface of the substrate by applying acrylic resin (product name "JEM-477", manufactured by JSR Corporation) using a coating apparatus. Such a stack of the substrate and the insulating layer was wound around a feed roller (not shown). Further, as a pattern of a first electrode layer, an organic layer, a second electrode layer, and a sealing layer, the pattern shown in FIG. 2 was employed.

With the stack wound in a roll being continuously unwound from the feed roller, an Al layer (anode layer) having a thickness of 100 nm that serves as the first electrode layer **23**, a HAT-CN (1,4,5,8,9,12-hexaazatriphenylene hexacarbonitrile) layer having a thickness of 10 nm that serves as a hole injection layer of the organic layer **25**, an NPB layer having a thickness of 50 nm that serves as a hole transporting layer thereof, an Alq3 layer having a thickness of 45 nm that serves as a light emitting layer and an electron transporting layer thereof, and a LiF layer having a thickness of 0.5 nm that serves as an electron injection layer thereof were thermally deposited in this order on the insulating layer **31** of the thus unwound stack. Thereafter, a Mg/Ag layer (cathode layer) having a thickness of 5/15 nm was co-deposited as the second electrode layer **27**. Further, an ITO layer (cathode layer) having a thickness of 50 nm was formed by sputtering. Thereafter, SiOCN having a thickness of 0.4 μm was deposited as the sealing layer **29** by plasma assisted deposition. The thus obtained stack (organic EL device **20**) was wound up on a take-up roller.

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After the completion of the winding, the aforementioned stack was unwound and was cut into a specific length. Thus, the organic EL device **20** of Example 1 (length: 80 mm \times width: 30 mm) was obtained (see FIG. 3).

Example 2

The organic EL device **20** of Example 2 was produced in the same manner as in Example 1 except that the pattern shown in FIG. 4 was employed as a pattern of the first electrode layer **23**, the organic layer **25**, the second electrode layer **27**, and the sealing layer **29** (see FIG. 5).

Example 3

A LiF layer having a thickness of 0.5 nm that serves as a hole injection layer of the organic layer, an Alq3 layer having a thickness of 45 nm that serves as a light emitting layer and an electron transporting layer thereof, NPB having a thickness of 50 nm that serves as a hole transporting layer thereof, and CuPc having a thickness of 10 nm that serves as an electron injection layer thereof were thermally deposited in this order. Further, an ITO layer (cathode layer) having a thickness of 50 nm was formed by sputtering as a second electrode layer. Thereafter, SiOCN having a thickness of 400 nm was deposited as a sealing layer by plasma assisted deposition. Except for these points, the same configuration as that of Example 1 was employed. Further, the pattern shown in FIG. 2 was employed. Thus, the organic EL device **20** of Example 3 (length: 80 mm \times width: 30 mm) was obtained (see FIG. 3).

Comparative Example 1

The organic EL device **50** of Comparative Example 1 was produced in the same manner as in Example 1 except that the pattern shown in FIG. 6 was employed.

Comparative Example 2

The organic EL device **50** of Comparative Example 2 was produced in the same manner as in Example 1 except that the pattern shown in FIG. 7 was employed.

Comparative Example 3

The organic EL device **50** of Comparative Example 3 was produced in the same manner as Example 1 except that the pattern shown in FIG. 8 was employed.

Comparative Example 4

The organic EL device **50** of Comparative Example 4 was produced in the same manner as Example 1 except that the pattern shown in FIG. 9 was employed.

Comparative Example 5

The organic EL device **50** of Comparative Example 5 was produced in the same manner as in Example 3 except that the pattern shown in FIG. 6 was employed.

Evaluation of Lifetime of Organic EL Device

Each of the thus obtained organic EL devices emitting no light was stored in a thermo-hygrostat set to 60° C./90% RH. The organic EL device was taken out at every specific time point from the start of storage, and was caused to emit light. The area of the light emitting part (area of the region emitting

light) was measured. The relationship between the storage time and the area of the light emitting part was plotted on a graph. Then, the time at which the area of the light emitting part started decreasing was taken as the lifetime of the organic EL device. The area of the light emitting part was measured using a digital microscope (product name: VHX-1000), manufactured by KEYENCE CORPORATION. Table 1 shows the results.

In Examples 1 to 3, both end edges of the organic layer were covered by both end sides of the second electrode layer (cathode layer), on both outer sides of the light emitting part in the longitudinal direction of the substrate. In Comparative Examples 1 to 5, at least one of both end edges of the organic layer was not covered by the cathode layer. As shown in Table 1, as a result of comparison of Examples 1 to 3 with Comparative Examples 1 to 5, the lifetime of Examples 1 to 3 was longer than the lifetime of Comparative Examples 1 to 5 by 1.5 times or more. These results revealed that the organic EL devices obtained by the manufacturing method of the present invention can suppress a deterioration in the light emission properties, and has excellent long-term stability.

It should be noted that, although an organic insulating layer was used as an insulating layer in the aforementioned examples, the effects of the present invention could be obtained in the same manner also in the case of using an inorganic insulating layer.

TABLE 1

| | Lifetime (hr) |
|----------|---------------|
| Ex. 1 | 660 |
| Ex. 2 | 680 |
| Ex. 3 | 640 |
| C. Ex. 1 | 350 |
| C. Ex. 2 | 390 |
| C. Ex. 3 | 370 |
| C. Ex. 4 | 370 |
| C. Ex. 5 | 340 |

REFERENCE SIGNS LIST

- 20: Organic EL Device
 - 21: Substrate
 - 23: Anode Layer (First Electrode Layer)
 - 25: Organic Layer
 - 25a: Light Emitting Layer (Organic Constituent Layer)
 - 27: Cathode Layer (Second Electrode Layer)
 - 29: Sealing Layer
 - 40: Light Emitting Part
- The invention claimed is:
1. A method for manufacturing an organic EL device, comprising:
- sequentially forming an insulating layer, a first electrode layer, an organic layer having at least a light emitting layer as an organic constituent layer, a second electrode

- layer, and a sealing layer, on one surface of a strip-shaped metal substrate; and thereby
- manufacturing the organic EL device having a portion in which the first electrode layer, the organic layer, and the second electrode layer overlap and which serves as a light emitting part, wherein
- while the first electrode layer and the second electrode layer are prevented from being in contact with each other,
- the first electrode layer, the organic layer, and the second electrode layer are formed so that both end edges of the organic layer in a longitudinal direction of the substrate are covered by both end sides of the second electrode layer in the longitudinal direction, on at least both outer sides of the light emitting part in the longitudinal direction of the substrate, by allowing the organic layer to protrude from the first electrode layer toward at least both outer sides of the substrate in the longitudinal direction and further allowing the second electrode layer to protrude from the organic layer toward at least both outer sides of the substrate in the longitudinal direction.
- 2. The method for manufacturing an organic EL device according to claim 1, wherein
- the substrate has a surface roughness in the longitudinal direction that is smaller than a surface roughness in the lateral direction.
- 3. An organic EL device comprising:
- an insulating layer; a first electrode layer; an organic layer having at least a light emitting layer as an organic constituent layer; a second electrode layer; and a sealing layer, which are sequentially formed on one surface of a strip-shaped metal substrate,
- the organic EL device having a portion in which the first electrode layer, the organic layer, and the second electrode layer overlap and which serves as a light emitting part, wherein
- the first electrode layer and the second electrode layer are not in contact with each other, and
- both end edges of the organic layer in the longitudinal direction of the substrate are covered by both end sides of the second electrode layer in the longitudinal direction, on at least both outer sides of the light emitting part in the longitudinal direction of the substrate, with a configuration where the organic layer protrudes from the first electrode layer toward at least both outer sides in a longitudinal direction of the substrate, and the second electrode layer also protrudes from the organic layer toward at least both outer sides in the longitudinal direction.
- 4. The organic EL device according to claim 3, wherein
- the substrate has a surface roughness in the longitudinal direction that is smaller than a surface roughness in the lateral direction.

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